

IN THE CLAIMS

Applicant here presents all claims, claims 1 through 12, including the status of each claim in the application as follows:

1-9 (Canceled)

10. (New) A cooling assembly comprising

a cold plate assembly including at least one heat pipe and at least one heat exchanger engaging and thermally connected to the at least one heat pipe and adapted for internally circulating a thermally conductive fluid therethrough;

heat generating electronic components in thermal conductivity with the at least one heat pipe;

a cooling system including a circuit having at least one circulating pump, at least one liquid to air heat exchanger and the heat exchanger engaging and thermally connected to the at least one heat pipe.

11. (new) A cooling assembly comprising

a cold plate assembly including at least one heat pipe and at least one heat exchanger engaging and thermally connected to the at least one heat pipe and adapted for internally circulating a thermally conductive fluid therethrough;

heat generating electronic components in thermal conductivity with the at least one heat pipe;

a cooling system including a circuit having at least one circulating pump, at least one liquid to liquid heat exchanger and the heat exchanger engaging and thermally connected to the at least one heat pipe.

12. (new) A cooling assembly comprising

a cold plate assembly including at least one heat pipe and at least one heat exchanger engaging and thermally connected to the at least one heat pipe and adapted for internally circulating a thermally conductive fluid therethrough;

heat generating electronic components in thermal conductivity with the at least one heat pipe;

a cooling system including a circuit having at least one circulating pump, at least one liquid to space radiator heat exchanger and the heat exchanger engaging and thermally connected to the at least one heat pipe.

Amendment Drawings

FIG 1A Prior Art Drawing Amended

FIG 1B Prior Art Drawing Amended

FIG. 5 is a top plan view of a cold plate assembly according to the invention;

FIG. 6 is an enlarged cross-sectional view of the cold plate assembly attached to a printed circuit board shown taken along line 2-2 of FIG. 1;

FIG. 7 is a top plan view of a cold plate assembly using individual heat pipes;

FIG. 8 is an enlarged cross-sectional view of a cold plate assembly attached to a printed circuit board shown taken along line 4-4 of Fig. 3;

FIG. 9 is a cross-sectional view of a cold plate assembly using individual heat pipes attached to a printed circuit board shown taken along line 5-5 of Fig. 3; and

FIG. 10 is a block diagram illustrating steps employed according to one embodiment of the method of the present invention